LC898111AXB

CMOS LSI

Optical Image Stabilization (OIS) Controller & Driver



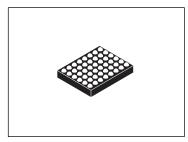
www.onsemi.com

Overview

The LC898111AXB is Optical Image Stabilization (OIS) system control LSI for smartphone camera modules.

The LSI have built-in digital signal processing circuits, such as a 2ch saturation H-Bridge Driver and a Flexible Filter circuit, and control VCM type actuators.

The LC898111AXB is identical LSI except for the dimensions, i.e. XB has WLP thickness, max. 0.69 mm with B/C.



WLCSP48, 3.22x2.57

Function

- Digital signal processing LSI (Logic LSI)
- Built-in digital servo circuit
- Built-in Gyro filter
- AD converter
 - 12-bit
 - input 5ch
 - Equipped with a sample-hold circuit
- DA converter
 - 8-bit
 - Output 2ch (Constant current Bias : max 7mA)
- Built-in Serial I/F circuit (2-wire I²C-Bus or 4-wire SPI Bus interface)
- Built-in Hall Bias circuit
- Built-in Hall Amp

(Gain of Opamp: x25, x50, x75, x100, x150, x200)

- Built-in OSC (Oscillator) 48MHz ± 5% (Frequency adjustment function)
- External Clock input is possible from TSTCLK (48MHz ± 5%)
- Built-in LDO (Low Drop-Out regulator)
- Digital Gyro I/F for the companies (SPI Bus) (Please refer for the details)
- Support Hall sensor and Photo Reflector as means to detect a position

- Motor Driver
- Saturation-drive H bridge x2ch
- IO max : 220mA
- Package
 - WLCSP48, 3.22mm x 2.57mm, thickness max 0.69mm, with B/C
- Pb-Free
- Halogen Free
- Power supply voltage
- Logic : DVDD30 = 2.6 to 3.6 V
 Driver : VM = 2.6 to 3.6 V

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

^{*} I²C Bus is a trademark of Philips Corporation.

Block Diagram

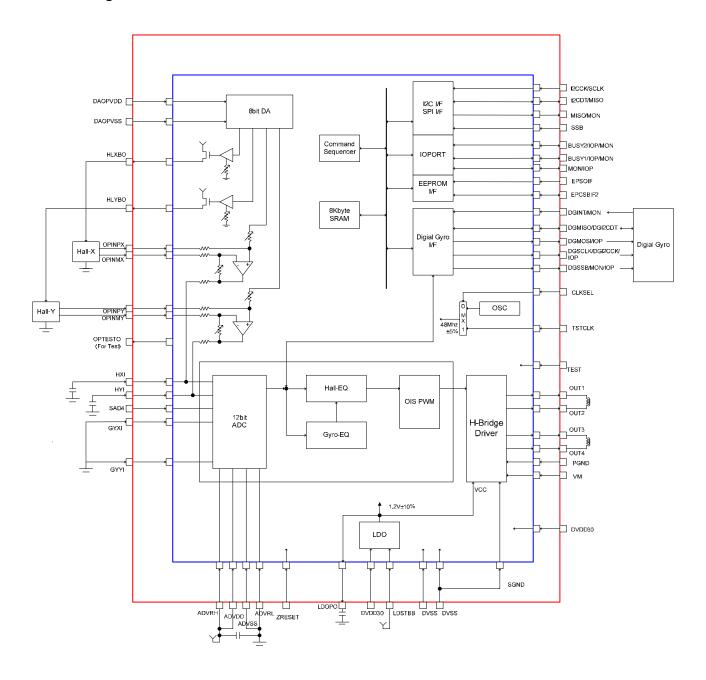


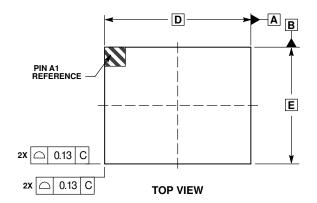
Figure 3.1 Example of wiring diagram (Hall) in LC898111AXB

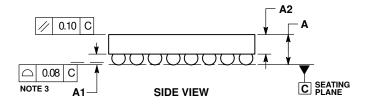
Package Dimensions

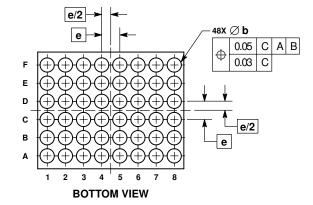
unit: mm

WLCSP48, 3.22x2.57

CASE 567GE **ISSUE O**







- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α		0.69	
A1	0.16	0.26	
A2	0.43 REF		
b	0.21	0.31	
D	3.22 BSC		
E	2.57 BSC		
е	0.40 BSC		

GENERIC MARKING DIAGRAM*



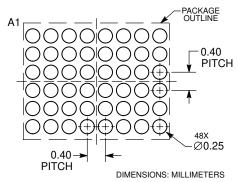
XXXXXXX = Device Code

= Assembly Location WL

= Wafer Lot YY = Year = Work Week ww = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

RECOMMENDED SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Pin Assignment

Top View

1	OPTESTO	OPINPY	ADVDD	ADVSS	GYYI	нхі
2	НЬХВО	OPINMY	ADVRH	GYXI	DVSS	I2CDT
3	EPSOIF	DAOPVDD	ADVRL	нүі	EPCSBIF2	I2CCK
4	DVDD30	DAOPVSS	OPINPX	SAD4	SSB	MISO
5	BUSY2	HLYBO	OPINMX	ZRESET	LDOPO	DVDD30
6	BUSY1	TEST	DVSS	TSTCLK	LDSTBB	DGSCLK
7	VM	MON	CLKSEL	DGMOSI	DGMISO	DGINT
8	OUT4	ОПТЗ	OUT2	OUT1	PGND	DGSSB
!	F	Е	D	С	В	Α
Driver DAC OpAmp ADC					EEPROM i/f Logic GND IO VDD (2.6V Logic Core VD	

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<typ> I : INPUT, O : OUTPUT, B : BIDIRECTION, P : Power, GND

Ball No	Pin Name	type	Description	
F8	OUT4	0	Driver Output	
F7	VM	P	Driver VDD (2.6V to 3.6V)	
			EEPROM I/F (at I ² C type EEPROM) / BUSY1(O)	
F6	BUSY1	В	/ General-purpose IOPORT(B) / inner signal Monitor(O)	
F5	BUSY2	В	BUSY2(O) / General-purpose IOPORT(B) / inner signal Monitor(O)	
F4	DVDD30	Р	Logic IO VDD (2.6V to 3.6V)	
F3	EPSOIF	i	EEPROM I/F	
F2	HLXBO	0	Hall-X Bias (Current Drive)	
F1	OPTESTO	0	OpAmp Test out	
E8	OUT3	0	Driver output	
E7	MON	В	inner signal monitor / General-purpose IOPORT	
E6	TEST	1	SPI & External clock case sets "1" other cases set "0"	
E5	HLYBO	0	Hall-Y Bias (Current Drive)	
		P	,	
E4	DAOPVSS	P	DA&Opamp VSS	
E3	DAOPVDD	-	DA&Opamp VDD (2.6V to 3.6V)	
E2 E1	OPINMY	!	Hall-Y OpAmp input-	
	OPINPY	1	Hall-Y OpAmp input+	
D8	OUT2	0	Driver Output	
D7	CLKSEL	I	change pin of OSC(0) and External clock(1)	
D6	DVSS	P .	Logic GND	
D5	OPINMX	!	Hall-X OpAmp input-	
D4	OPINPX	!	Hall-X OpAmp input+	
D3	ADVRL	1	ADC Reference Voltage Low input	
D2	ADVRH	<u> </u>	ADC Reference Voltage High input	
D1	ADVDD	Р	AD VDD (2.6V to 3.6V)	
C8	OUT1	0	Driver Output	
C7	DGMOSI	В	Digital Gyro (4-wire)IF data(O) / HPS Control(O) / General-purpose IOPORT(B)	
C6	TSTCLK	I	CLKSEL=1: External Clock, CLKSEL=0: change pin of I ² C(0) and SPI(1)	
C5	ZRESET	I	Hard Wafer Reset	
C4	SAD4	I	General-purpose AD input	
C3	HYI	I	Hall-Y AD input	
C2	GYXI	I	Gyro-X AD input	
C1	ADVSS	Р	AD GND	
B8	PGND	Р	Driver GND	
B7	DGMISO	В	Digital Gyro SPI IF Data(I) / Digital Gyro I ² C IF Data(B)	
B6	LDSTBB	L	LDO Standby (0 : Standby On, 1 : Standby Off)	
B5	LDOPO	Р	LDO Power supply out (Logic Core VDD (1.14V to 1.26V))	
B4	SSB	- 1	SPI I/F Chip Select / VDD fix at I ² C i/f	
В3	EPCSBIF2	В	EEPROM I/F	
B2	DVSS	Р	Logic GND	
B1	GYYI	I	Gyro-Y AD input	
A8	DGSSB	В	Digital Gyro SPI IF Chip Select(O) / inner signal monitor(O) / General-purpose IOPORT(B)	
A7	DGINT	В	Digital Gyro SPI IF Data Busy(I) / inner signal monitor(O) / General-purpose IOPORT(B)	
	D000111		Digital Gyro SPI IF clock (O) / Digital Gyro I ² C IF clock(O) /	
A6	DGSCLK	В	HPS Control 1(O) / General-purpose IOPORT (B)	
A5	DVDD30	Р	Logic IO VDD (2.6V to 3.6V) and power supply to LDO	
A4	MISO	0	SPI I/F Data / General-purpose IOPORT / inner signal monitor	
A3	I2CCK	1	I ² C_IF clock / SPI IF clock	
		_		
A2	I2CDT	В	I ² C_IF Data(B) / SPI IF Data	

LC898111AXB

ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)
LC898111AXB-MH	WLCSP48, 3.22x2.57 (Pb-Free / Halogen Free)	4000 / Tape & Reel

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub_link/Collateral/BRD8011-D.PDF

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